

Product Texts

Low viscosity, self-extinguishing polyamide 12 compound, free of halogen and phosphorus

VESTAMID® X7166 NC is a heat stabilized PA 12 compound containing a non-migrating flame retardant, free of halogen and phosphorus. Tested according to UL94, VESTAMID® X7166 complies with the flammability class V-2.

Due to the halogen- and phosphorus-free flame retardants, VESTAMID® X7166 is especially suitable for the electronic and cable industry. It can be used for injection molding as well as for wire extrusion coating.

VESTAMID® X7166 is supplied as cylindrical granules, ready for processing, in moisture-proof bags.

Due to the flame retardants, the melt temperature should not exceed 260°C. We recommend melt temperatures within a range of 210°C to 230°C.

The use of colorants may affect property values.

Inside the original and undamaged packaging, the product has a shelf life of at least 2 years when stored in dry rooms at temperatures not exceeding 30°C.

For information about processing of VESTAMID®, please follow the general commendations about "[Processing of VESTAMID® compounds](#)".

The values presented are typical or average values, they do not constitute a specification.

FOR FURTHER INFORMATION PLEASE CONTACT US AT EVONIK-HP@EVONIK.COM OR VISIT OUR PRODUCT AT WWW.VESTAMID.COM

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melt volume-flow rate, MVR	108 / *	cm ³ /10min	ISO 1133
Temperature	250 / *	°C	-
Load	2.16 / *	kg	-
^[C] Molding shrinkage, parallel	0.7 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.8 / *	%	ISO 294-4, 2577
^[C] Density of melt	860	kg/m ³	-
^[C] Thermal conductivity of melt	0.2	W/(m K)	-
^[C] Spec. heat capacity of melt	3000	J/(kg K)	-

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	1890 / -	MPa	ISO 527
^[C] Yield stress	47 / -	MPa	ISO 527
^[C] Yield strain	5.8 / -	%	ISO 527
^[C] Nominal strain at break	20 / -	%	ISO 527
^[C] Charpy impact strength, +23°C	57 / -	kJ/m ²	ISO 179/1eU
^[C] Type of failure	C / -	-	-
^[C] Charpy impact strength, -30°C	80 / -	kJ/m ²	ISO 179/1eU
^[C] Type of failure	C / -	-	-
^[C] Charpy notched impact strength, +23°C	3 / -	kJ/m ²	ISO 179/1eA
^[C] Type of failure	C / -	-	-
^[C] Charpy notched impact strength, -30°C	5 / -	kJ/m ²	ISO 179/1eA
^[C] Type of failure	C / -	-	-

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	178 / *	°C	ISO 11357-1/-3
^[C] Glass transition temperature, 10°C/min	41 / *	°C	ISO 11357-1/-2
^[C] Temp. of deflection under load, 1.80 MPa	50 / *	°C	ISO 75-1/-2

^[C] Temp. of deflection under load, 0.45 MPa	140 / *	°C	ISO 75-1/-2
^[C] Vicat softening temperature, B	150 / *	°C	ISO 306
^[C] Burning Behav. at 1.5 mm nom. thickn.	V-2 / *	class	IEC 60695-11-10
Thickness tested	1.6 / *	mm	-
^[C] Burning Behav. at thickness h	V-2 / *	class	IEC 60695-11-10
Thickness tested	0.8 / *	mm	-
Yellow Card available	yes / *	-	-
^[C] Oxygen index	34 / *	%	ISO 4589-1/-2

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Relative permittivity, 1MHz	3.6 / -	-	IEC 62631-2-1
^[C] Dissipation factor, 1MHz	340 / -	E-4	IEC 62631-2-1
^[C] Volume resistivity	1E12 / -	Ohm*m	IEC 62631-3-1
^[C] Electric strength	28 / -	kV/mm	IEC 60243-1
^[C] Comparative tracking index	600 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Water absorption	1.3 / *	%	Sim. to ISO 62
^[C] Humidity absorption	0.6 / *	%	Sim. to ISO 62
^[C] Density	1070 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Test specimen production	Value	Unit	Test Standard
ISO Data			
^[C] Injection Molding, melt temperature	220	°C	ISO 294
Injection Molding, mold temperature	80	°C	ISO 294
Injection Molding, injection velocity	200	mm/s	ISO 294
Injection Molding, pressure at hold	70	MPa	ISO 294

[C]: CAMPUS

Characteristics

Processing

Injection Molding, Profile Extrusion, Wire/Cable Extrusion, Other Extrusion, Coating

Delivery form

Pellets, Natural Color

Special Characteristics

Flame retardant, Halogen-free, Phosphorus-free, Heat stabilized or stable to heat

Applications

Electrical and Electronical

Regional Availability

North America, Europe, Asia Pacific, South and Central America, Near East/Africa